

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the applications.

LISTING OF CLAIMS:

1. (Currently Amended) A sintering method for a W-Cu composite material without exuding of Cu comprising the steps of:

holding the a W-Cu composite material ~~prepared by compacting a W-Cu composite powder for 0.5[[~]] -10 hours at 800[[~]] -1083°C (except 1083°C) which is a Cu solid phase temperature range~~ under a reduction temperature atmosphere; and

sintering the W-Cu composite material by increasing temperature to 1200[[~]] -1400°C and thereby cooling without a holding time.

2. (Currently Amended) A sintering method for a W-Cu composite material without exuding of Cu comprising the steps of:

holding the a W-Cu composite material ~~prepared by compacting a W-Cu composite powder for 0.5[[~]] -10 hours at 1083[[~]] -1150°C (except 1083°C) which is just above a Cu melting point~~ under a reduction temperature atmosphere; and

sintering the W-Cu composite material by increasing temperature to 1200[[~]] -1400°C and thereby cooling without a holding time.

3. (Currently Amended) The method of claim 1 or 2, wherein the W-Cu composite powder ~~prepared by a method disclosed in the Korean patent application No. 24857 in 2002~~ is prepared by mixing WO₃/WO_{2.9} with CuO/Cu₂O, milling, and performing a heat treatment for reduction at a hydrogen atmosphere, and has a round shape of a certain size that W powder

surrounds Cu powder.

Please add the following new claims:

4. (New) The method of claim 2, wherein the W-Cu composite powder is prepared by mixing $WO_3/WO_{2.9}$ with CuO/Cu_2O , milling, and performing a heat treatment for reduction at a hydrogen atmosphere, and has a round shape of a certain size that W powder surrounds Cu powder.

5. (New) The method of claim 1, wherein the W-Cu composite is prepared by compacting a W-Cu composite powder.

6. (New) The method of claim 2, wherein the W-Cu composite is prepared by compacting a W-Cu composite powder.